

AMENDMENTS TO THE CLAIMS

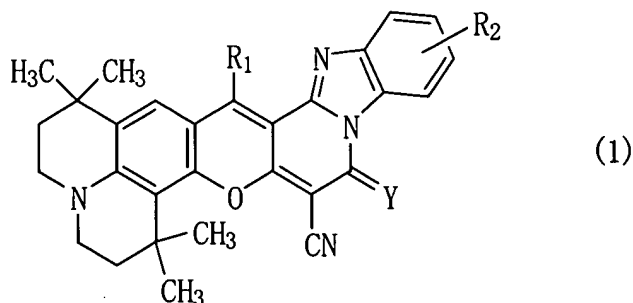
Please cancel claim 5 without prejudice or disclaimer. Please amend claim 1 as follows:

Claim 1 (Currently amended): A negative photosensitive resin composition comprising:

- (A) a photocurable resin having a photosensitive group or groups crosslinkable by light irradiation,
(B) a photoacid generator, ~~and~~
(C) a photosensitizer which is a benzopyran condensed ring compound capable of increasing photosensitivity to visible light with a wavelength of 480 nm or more, and
(D) a photoacid proliferating agent which is an organic acid ester.

Claim 2 (Original): A composition according to claim 1, wherein the proportion of the photoacid generator (B) is about 0.01 to 10 parts by weight per 100 parts by weight of the resin (A).

Claim 3 (Original): A composition according to claim 1, wherein the photosensitizer (C) is a benzopyran condensed ring compound represented by Formula (1)



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wherein R₁ is hydrogen, halogen, cyano, trifluoromethyl, carboxyl or carboxylic acid ester, R₂ is hydrogen, alkyl, alkoxy, cyano, trifluoromethyl, sulfoxy or halogen, and Y is NH or O.

Claim 4 (Original): A composition according to claim 1, wherein the proportion of the photosensitizer (C) is about 0.1 to 10 parts by weight per 100 parts by weight of the total amount of the resin (A) and photoacid generator (B).

Claim 5 (Canceled).

Claim 6 (Original): A composition according to claim 1 which is an organic solvent-based resin composition.

Claim 7 (Original): A composition according to claim 1 which is an aqueous resin composition.

Claim 8 (Original): A negative photosensitive dry film prepared by applying a negative photosensitive resin composition according to claim 1 to a surface of support film, followed by drying, to form a negative photosensitive resin layer.

Claim 9 (Original): A method of forming a pattern comprising the steps of:

- (1) applying a negative photosensitive resin composition according to claim 1 to a substrate, followed by drying, to form a negative photosensitive resin coating,
- (2) irradiating the resin coating with visible light directly or through a mask so as to obtain a desired pattern, and
- (3) removing the unirradiated part of the negative photosensitive resin coating by development to form a resist pattern coating.

Claim 10 (Original): A method of forming a pattern comprising the steps of:

- (1') attaching a negative photosensitive dry film according to claim 8 to a substrate so that the photosensitive resin layer of the dry film is in contact with the substrate to form a negative photosensitive resin coating, and optionally peeling off the support film of the dry film,
- (2) irradiating the resin coating with visible light directly or through a mask so as to obtain a desired pattern, and
- (3') peeling off the support film of the dry film when the support film has not been peeled off, and removing the unirradiated part of the negative photosensitive resin coating by development to form a resist pattern coating.